RJR Polymers to Showcase Innovative LCP Technology at European Microwave Week

Product line Demo, Conference Paper to Highlight Thermal Management Advantages of New Packaging Approach

Oakland, Calif. – September, xx, 2010 – RJR Polymers, a leading developer of high performance semiconductor packaging, announced today that it will maintain a high profile at this year's European Microwave Week, the leading conference in Europe for microwave, RF, wireless and radar technology held September 28 through October 1 at CNIT in Paris. As part of its plans, the company will exhibit the latest advances in its revolutionary Liquid Crystal Polymer (LCP) semiconductor packaging technology, including its new QFN packages, at the conference. In addition, company consultant Andy Longford will deliver a paper on how to develop customized thermal management solutions for RF devices using LCP packaging.

"The continually rising performance of today's RF and microwave devices has placed a high priority on thermal management considerations," noted Dave DeWire, director of sales and marketing at RJR Polymers. "By attaching Liquid Crystal Polymer housings to plated metal substrates and other material using our unique bonding materials, we have developed a highly flexible, highly reliable air cavity semiconductor packaging line that offers OEMs the opportunity to optimize thermal performance to a wide range of semiconductors in a low cost, near-hermetic solution. Moreover, over the past several years this revolutionary technology has been proven in the highly competitive cellular infrastructure market with the sale of over two million LCP packages."

Unmatched Design Flexibility at Low Cost

RJR's LCP technology allows OEMs an unprecedented combination of performance, design flexibility and cost compared to traditional RF and microwave packaging solutions. It supports a wider range of power levels and frequencies than competitive packaging technologies by allowing the use of very high thermal conductivity materials, including copper, and by tolerating components with mismatched coefficients of expansion (CTE). At the same time, this unique technology reduces cost and shortens time-to-market by allowing customers to easily develop different products by simply creating a single injection mold and swapping out the lead frame. RJR will demonstrate its entire LCP product family, including its' newest QFN product line, in booth 200 of the exhibition.

Longford's paper, entitled "LCP Device Housing Enables Selective Thermal Management for RF Device Packages", will be part of the conference's "New Trends for Packaging in industrial Applications" Session. The paper will describe the high degree of flexibility RJR's technology offers by discussing the 3-piece construction of the package, the wide range of interchangeable substrates available and the intrinsic advantages of the LCP material. The presentation will compare the various housing options the technology offers and how OEMs can support the use of a wide range of ICs by tailoring a package's CTE to optimize thermal performance. It will also outline how this technology can be built to industry standard package outlines or modified for custom solutions. Longford will deliver his presentation on Wednesday, September 29 at 16:00.

About RJR Polymers

RJR Polymers, Inc. is a developer of LCP semiconductor packaging, epoxies, epoxy-coated lids and sealing equipment for a wide variety of applications in the RF, cellular, automotive, optical, imaging, avionics and sensor markets as well as emerging applications in solar power, high-power LEDs and system-level solutions that require extremely high levels of integration. The company's patented, injection-molded, Liquid Crystal Polymer (LCP) packaging technology offers superior performance, design flexibility and cost advantages over traditional ceramic and over-molded packaging solutions. RJR Polymers Inc. is a privately-held company based in Oakland, California. For more information, please visit the company's website at www.rjrpolymers.com.